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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	24MHz
Connectivity	I <sup>2</sup> C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I <sup>2</sup> S, POR, PWM, WDT
Number of I/O	17
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	24-VQFN Exposed Pad
Supplier Device Package	24-QFN (5x5)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/silicon-labs/efm32zg108f32-qfn24">https://www.e-xfl.com/product-detail/silicon-labs/efm32zg108f32-qfn24</a>

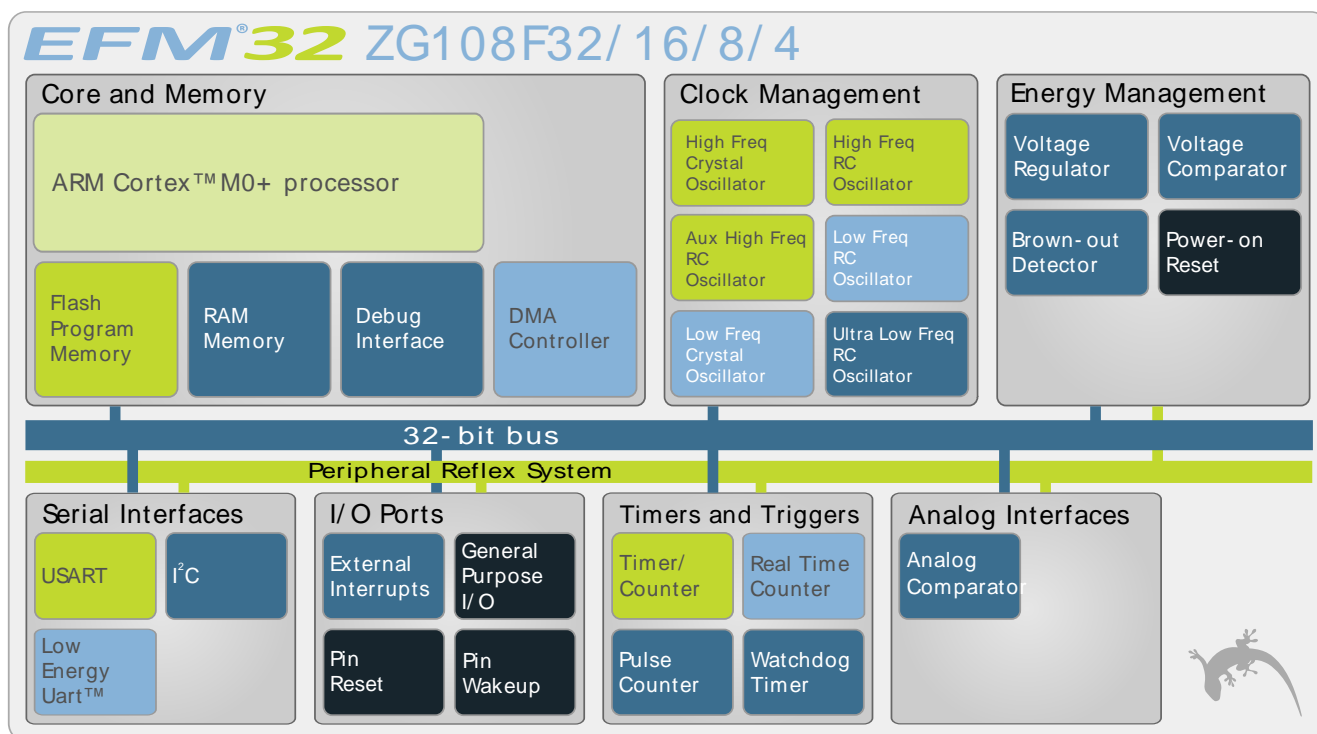
## 2 System Summary

### 2.1 System Introduction

The EFM32 MCUs are the world's most energy friendly microcontrollers. With a unique combination of the powerful 32-bit ARM Cortex-M0+, innovative low energy techniques, short wake-up time from energy saving modes, and a wide selection of peripherals, the EFM32ZG microcontroller is well suited for any battery operated application as well as other systems requiring high performance and low-energy consumption. This section gives a short introduction to each of the modules in general terms and also shows a summary of the configuration for the EFM32ZG108 devices. For a complete feature set and in-depth information on the modules, the reader is referred to the *EFM32ZG Reference Manual*.

A block diagram of the EFM32ZG108 is shown in Figure 2.1 (p. 3) .

**Figure 2.1. Block Diagram**



#### 2.1.1 ARM Cortex-M0+ Core

The ARM Cortex-M0+ includes a 32-bit RISC processor which can achieve as much as 0.9 Dhrystone MIPS/MHz. A Wake-up Interrupt Controller handling interrupts triggered while the CPU is asleep is included as well. The EFM32 implementation of the Cortex-M0+ is described in detail in *ARM Cortex-M0+ Devices Generic User Guide*.

#### 2.1.2 Debug Interface (DBG)

This device includes hardware debug support through a 2-pin serial-wire debug interface .

#### 2.1.3 Memory System Controller (MSC)

The Memory System Controller (MSC) is the program memory unit of the EFM32ZG microcontroller. The flash memory is readable and writable from both the Cortex-M0+ and DMA. The flash memory is divided into two blocks; the main block and the information block. Program code is normally written to the main block. Additionally, the information block is available for special user data and flash lock bits. There is also a read-only page in the information block containing system and device calibration data. Read and write operations are supported in the energy modes EM0 and EM1.

## 2.1.4 Direct Memory Access Controller (DMA)

The Direct Memory Access (DMA) controller performs memory operations independently of the CPU. This has the benefit of reducing the energy consumption and the workload of the CPU, and enables the system to stay in low energy modes when moving for instance data from the USART to RAM or from the External Bus Interface to a PWM-generating timer. The DMA controller uses the PL230  $\mu$ DMA controller licensed from ARM.

## 2.1.5 Reset Management Unit (RMU)

The RMU is responsible for handling the reset functionality of the EFM32ZG.

## 2.1.6 Energy Management Unit (EMU)

The Energy Management Unit (EMU) manage all the low energy modes (EM) in EFM32ZG microcontrollers. Each energy mode manages if the CPU and the various peripherals are available. The EMU can also be used to turn off the power to unused SRAM blocks.

## 2.1.7 Clock Management Unit (CMU)

The Clock Management Unit (CMU) is responsible for controlling the oscillators and clocks on-board the EFM32ZG. The CMU provides the capability to turn on and off the clock on an individual basis to all peripheral modules in addition to enable/disable and configure the available oscillators. The high degree of flexibility enables software to minimize energy consumption in any specific application by not wasting power on peripherals and oscillators that are inactive.

## 2.1.8 Watchdog (WDOG)

The purpose of the watchdog timer is to generate a reset in case of a system failure, to increase application reliability. The failure may e.g. be caused by an external event, such as an ESD pulse, or by a software failure.

## 2.1.9 Peripheral Reflex System (PRS)

The Peripheral Reflex System (PRS) system is a network which lets the different peripheral module communicate directly with each other without involving the CPU. Peripheral modules which send out Reflex signals are called producers. The PRS routes these reflex signals to consumer peripherals which apply actions depending on the data received. The format for the Reflex signals is not given, but edge triggers and other functionality can be applied by the PRS.

## 2.1.10 Inter-Integrated Circuit Interface (I2C)

The I<sup>2</sup>C module provides an interface between the MCU and a serial I<sup>2</sup>C-bus. It is capable of acting as both a master and a slave, and supports multi-master buses. Both standard-mode, fast-mode and fast-mode plus speeds are supported, allowing transmission rates all the way from 10 kbit/s up to 1 Mbit/s. Slave arbitration and timeouts are also provided to allow implementation of an SMBus compliant system. The interface provided to software by the I<sup>2</sup>C module, allows both fine-grained control of the transmission process and close to automatic transfers. Automatic recognition of slave addresses is provided in all energy modes.

## 2.1.11 Universal Synchronous/Asynchronous Receiver/Transmitter (USART)

The Universal Synchronous Asynchronous serial Receiver and Transmitter (USART) is a very flexible serial I/O module. It supports full duplex asynchronous UART communication as well as RS-485, SPI, MicroWire and 3-wire. It can also interface with ISO7816 SmartCards, IrDA and I2S devices.

### 2.1.12 Pre-Programmed UART Bootloader

The bootloader presented in application note AN0003 is pre-programmed in the device at factory. Auto-baud and destructive write are supported. The autobaud feature, interface and commands are described further in the application note.

### 2.1.13 Low Energy Universal Asynchronous Receiver/Transmitter (LEUART)

The unique LEUART<sup>™</sup>, the Low Energy UART, is a UART that allows two-way UART communication on a strict power budget. Only a 32.768 kHz clock is needed to allow UART communication up to 9600 baud/s. The LEUART includes all necessary hardware support to make asynchronous serial communication possible with minimum of software intervention and energy consumption.

### 2.1.14 Timer/Counter (TIMER)

The 16-bit general purpose Timer has 3 compare/capture channels for input capture and compare/Pulse-Width Modulation (PWM) output.

### 2.1.15 Real Time Counter (RTC)

The Real Time Counter (RTC) contains a 24-bit counter and is clocked either by a 32.768 kHz crystal oscillator, or a 32.768 kHz RC oscillator. In addition to energy modes EM0 and EM1, the RTC is also available in EM2. This makes it ideal for keeping track of time since the RTC is enabled in EM2 where most of the device is powered down.

### 2.1.16 Pulse Counter (PCNT)

The Pulse Counter (PCNT) can be used for counting pulses on a single input or to decode quadrature encoded inputs. It runs off either the internal LFACLK or the PCNTn\_S0IN pin as external clock source. The module may operate in energy mode EM0 - EM3.

### 2.1.17 Analog Comparator (ACMP)

The Analog Comparator is used to compare the voltage of two analog inputs, with a digital output indicating which input voltage is higher. Inputs can either be one of the selectable internal references or from external pins. Response time and thereby also the current consumption can be configured by altering the current supply to the comparator.

### 2.1.18 Voltage Comparator (VCMP)

The Voltage Supply Comparator is used to monitor the supply voltage from software. An interrupt can be generated when the supply falls below or rises above a programmable threshold. Response time and thereby also the current consumption can be configured by altering the current supply to the comparator.

### 2.1.19 General Purpose Input/Output (GPIO)

In the EFM32ZG108, there are 17 General Purpose Input/Output (GPIO) pins, which are divided into ports with up to 16 pins each. These pins can individually be configured as either an output or input. More advanced configurations like open-drain, filtering and drive strength can also be configured individually for the pins. The GPIO pins can also be overridden by peripheral pin connections, like Timer PWM outputs or USART communication, which can be routed to several locations on the device. The GPIO supports up to 11 asynchronous external pin interrupts, which enables interrupts from any pin on the device. Also, the input value of a pin can be routed through the Peripheral Reflex System to other peripherals.

## 2.2 Configuration Summary

The features of the EFM32ZG108 is a subset of the feature set described in the EFM32ZG Reference Manual. Table 2.1 (p. 6) describes device specific implementation of the features.

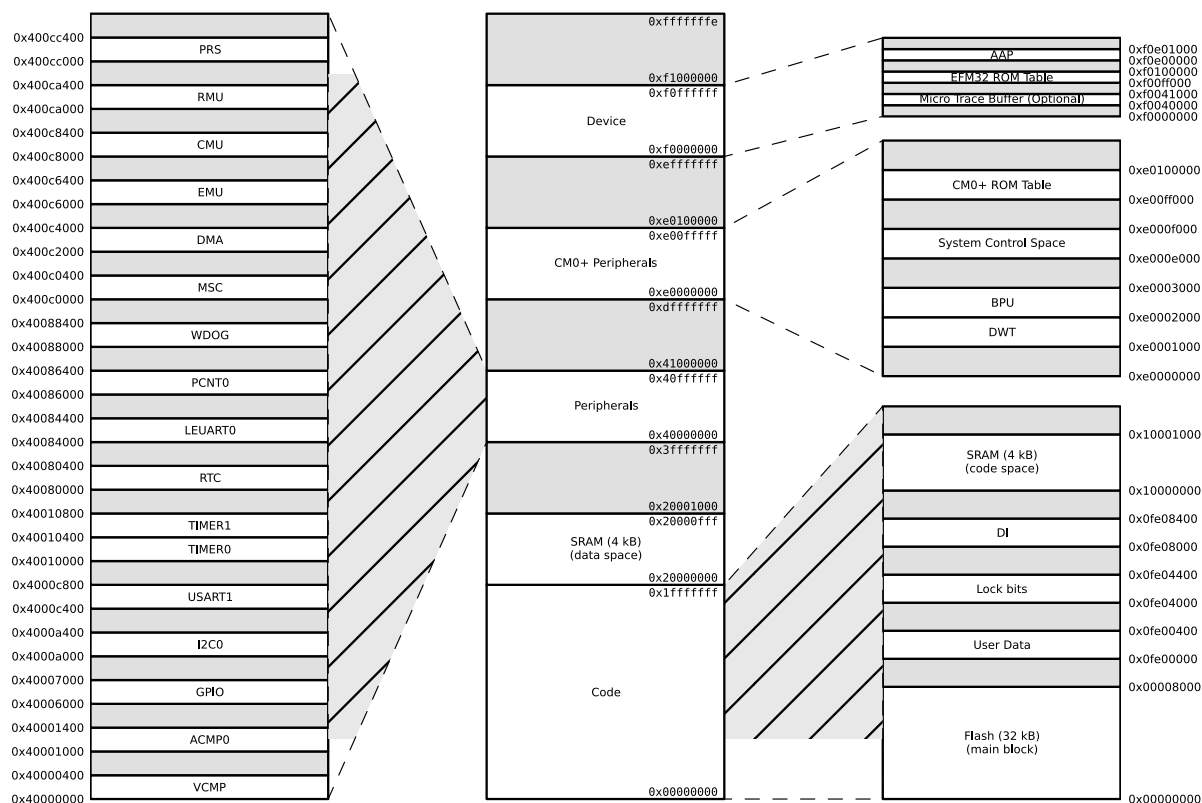
**Table 2.1. Configuration Summary**

Module	Configuration	Pin Connections
Cortex-M0+	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO,
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART1	Full configuration with I2S and IrDA	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration	TIM0_CC[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
RTC	Full configuration	NA
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[1:0], ACMP0_O
VCMP	Full configuration	NA
GPIO	17 pins	Available pins are shown in Table 4.3 (p. 40)

## 2.3 Memory Map

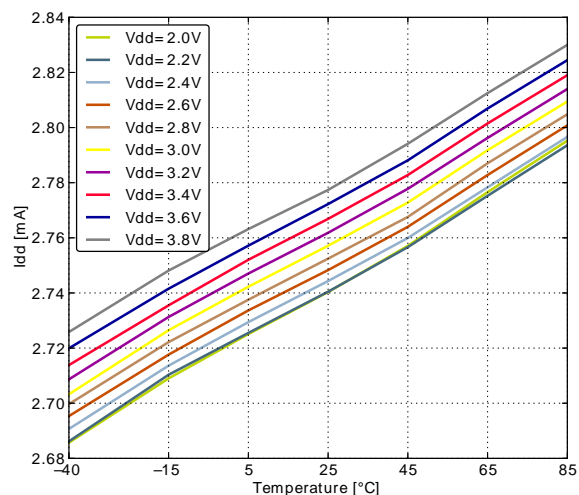
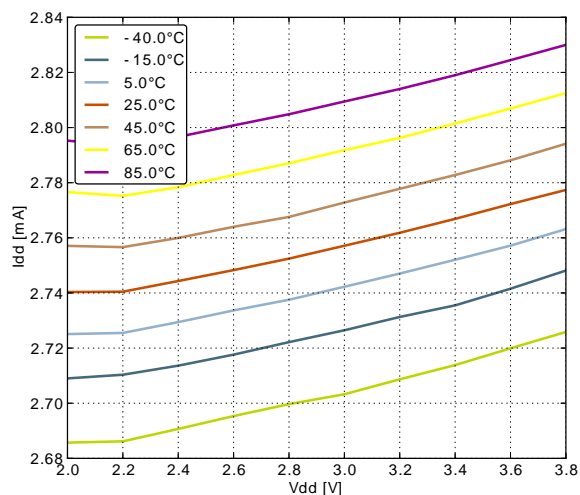
The *EFM32ZG108* memory map is shown in Figure 2.2 (p. 7), with RAM and Flash sizes for the largest memory configuration.

Figure 2.2. EFM32ZG108 Memory Map with largest RAM and Flash sizes

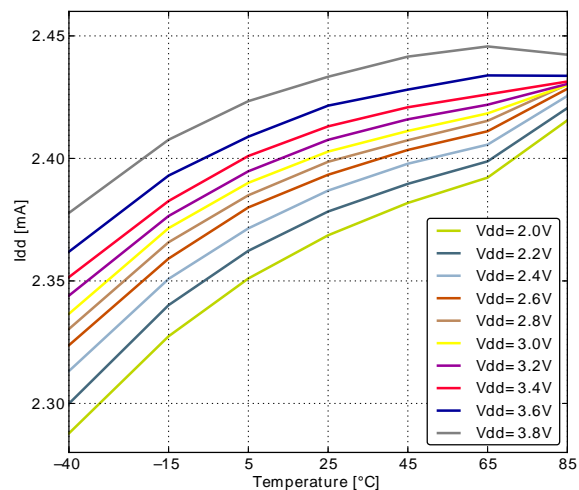
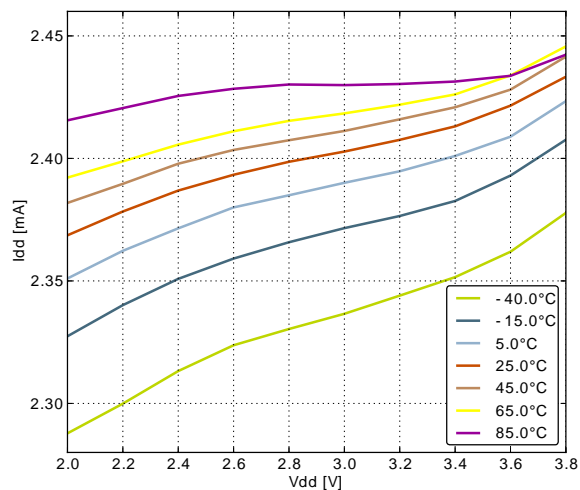


### 3.4.1 EM0 Current Consumption

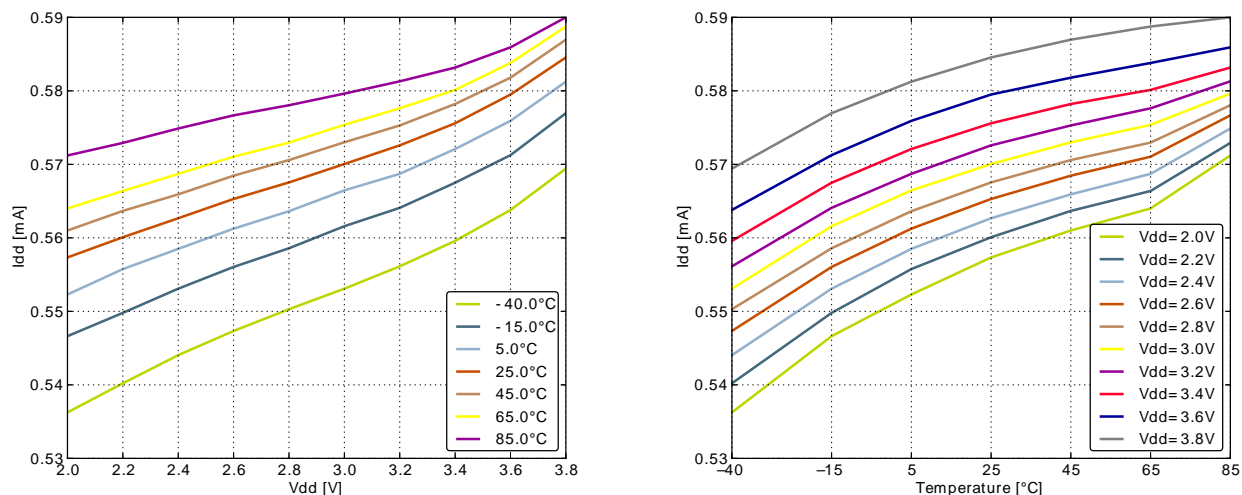
**Figure 3.1. EM0 Current consumption while executing prime number calculation code from flash with HFRCO running at 24 MHz**



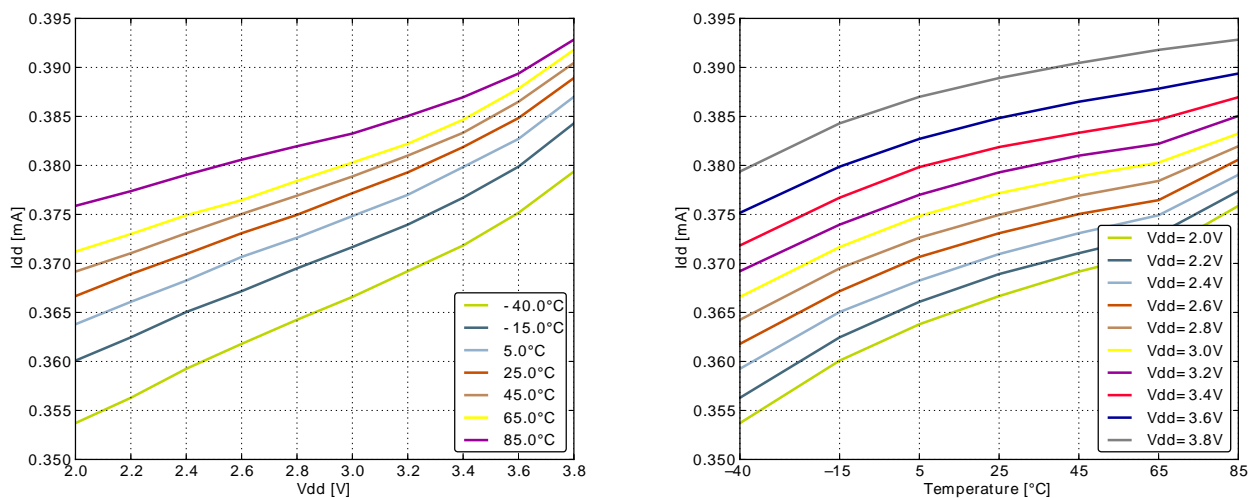
**Figure 3.2. EM0 Current consumption while executing prime number calculation code from flash with HFRCO running at 21 MHz**



**Figure 3.9. EM1 Current consumption with all peripheral clocks disabled and HFRCO running at 11 MHz**



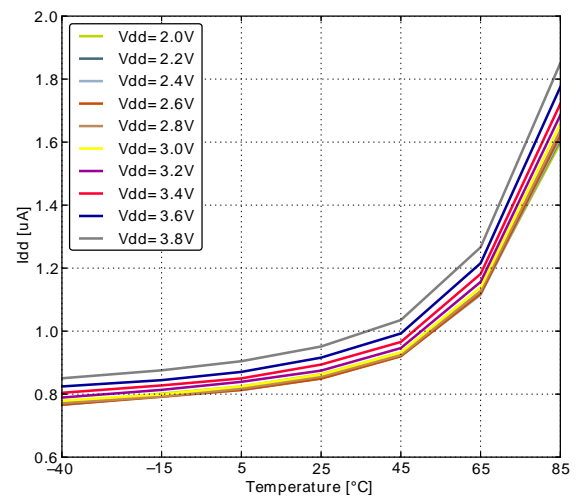
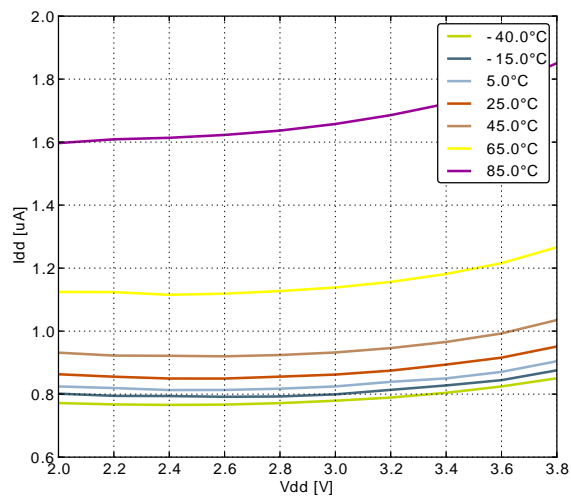
**Figure 3.10. EM1 Current consumption with all peripheral clocks disabled and HFRCO running at 6.6 MHz**





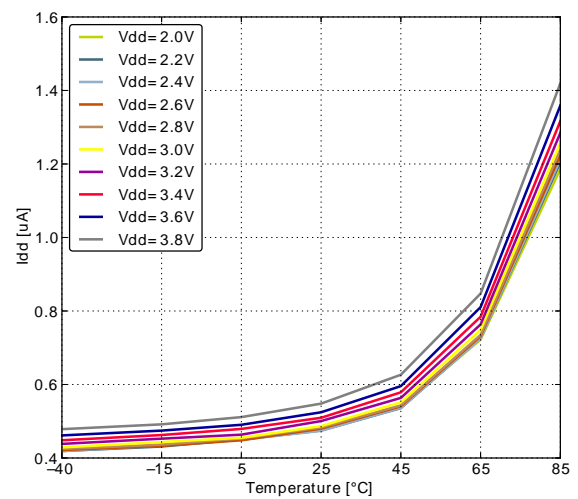
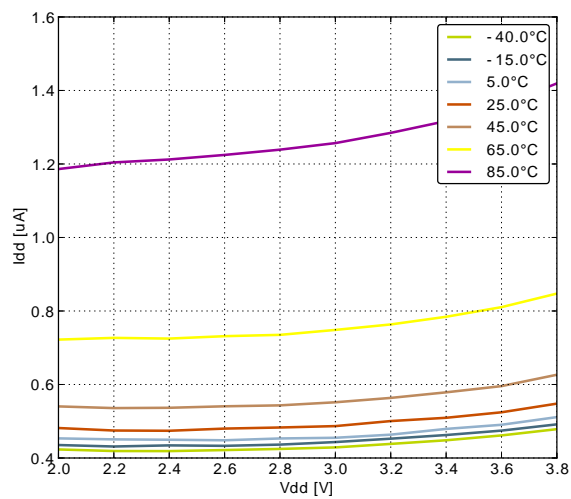
### 3.4.3 EM2 Current Consumption

Figure 3.11. EM2 current consumption. RTC prescaled to 1kHz, 32.768 kHz LFRCO.



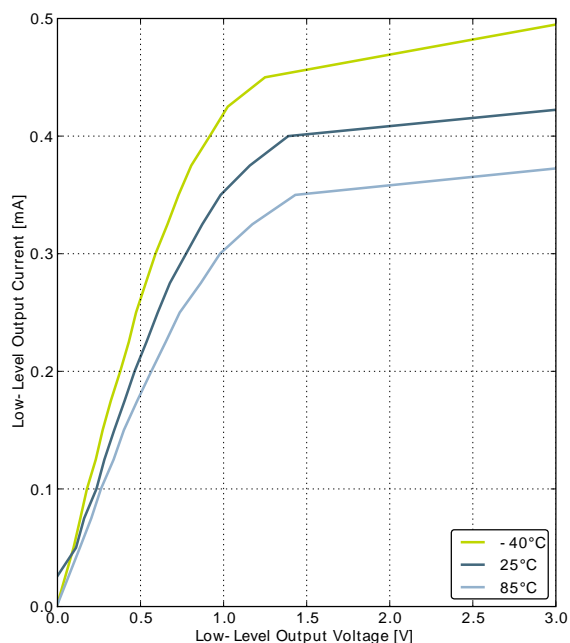
### 3.4.4 EM3 Current Consumption

Figure 3.12. EM3 current consumption.

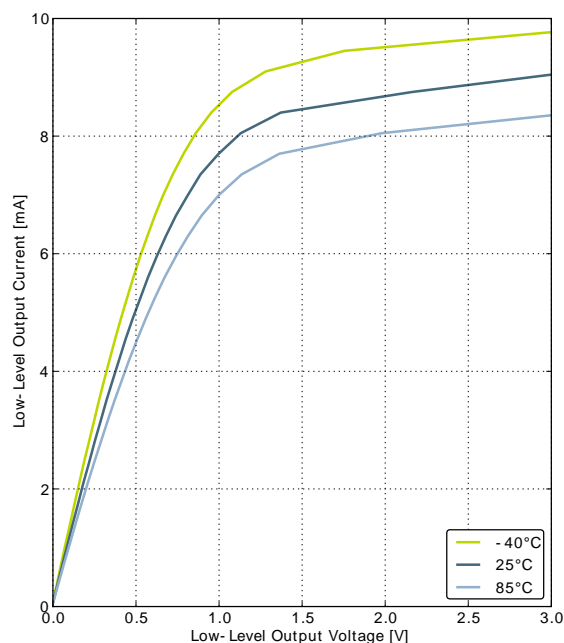


Symbol	Parameter	Condition	Min	Typ	Max	Unit
	by the glitch suppression filter					
$t_{IOOF}$	Output fall time	GPIO_Px_CTRL DRIVEMODE = LOWEST and load capacitance $C_L=12.5-25pF$ .	$20+0.1C_L$		250	ns
		GPIO_Px_CTRL DRIVEMODE = LOW and load capacitance $C_L=350-600pF$	$20+0.1C_L$		250	ns
$V_{IOHYST}$	I/O pin hysteresis ( $V_{IOTHR+} - V_{IOTHR-}$ )	$V_{DD} = 1.98 - 3.8 V$	$0.1V_{DD}$			V

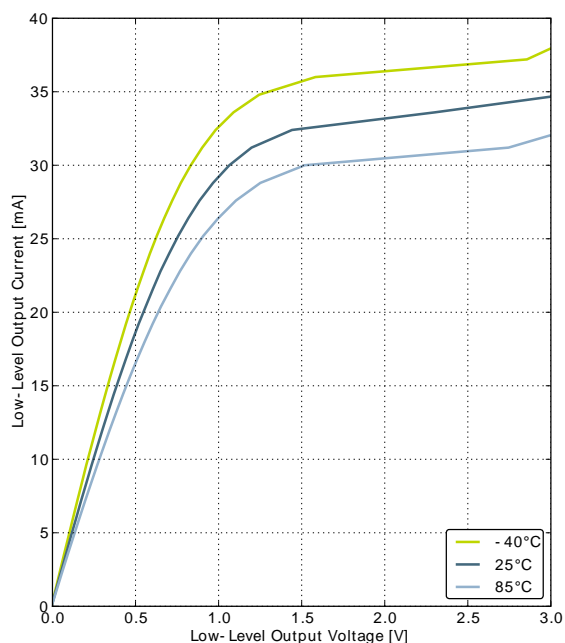
**Figure 3.16. Typical Low-Level Output Current, 3V Supply Voltage**



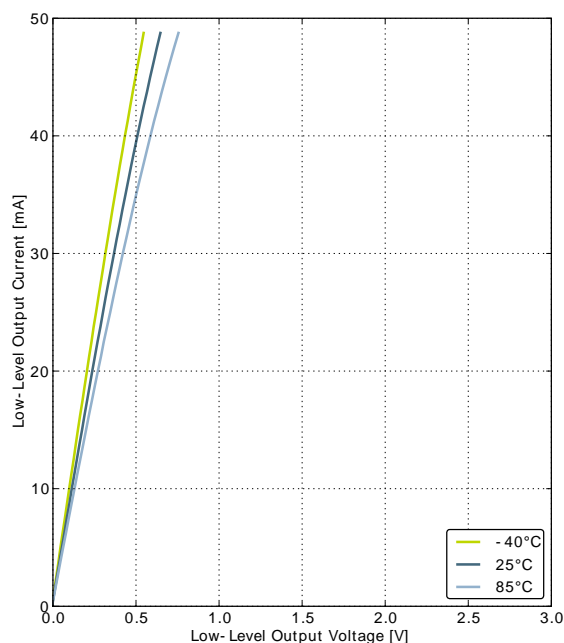
GPIO\_Px\_CTRL DRIVEMODE = LOWEST



GPIO\_Px\_CTRL DRIVEMODE = LOW

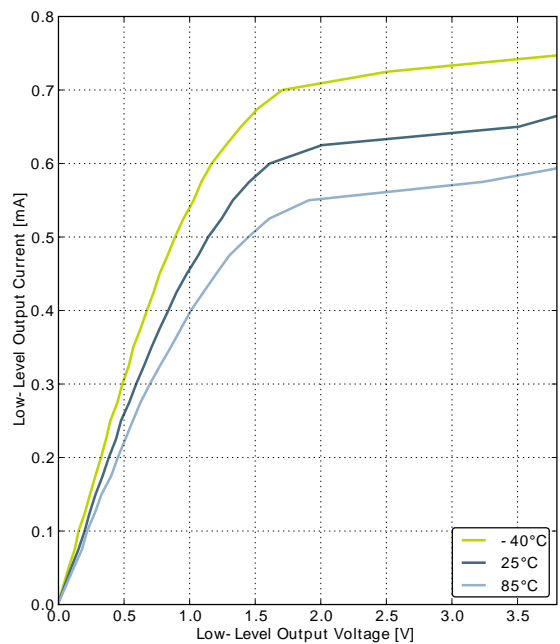


GPIO\_Px\_CTRL DRIVEMODE = STANDARD

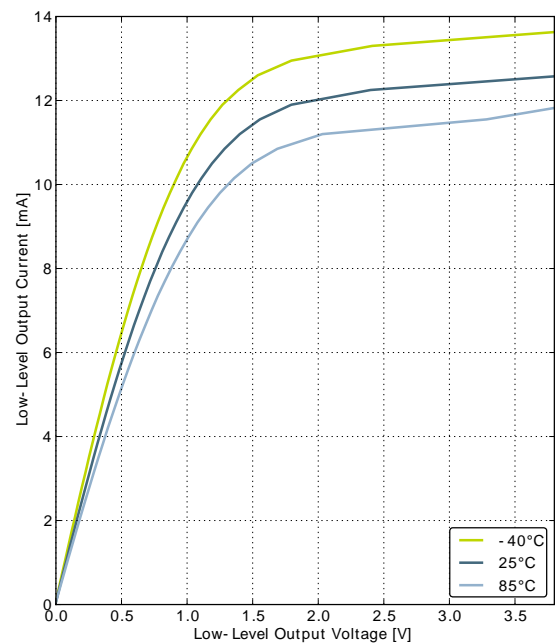


GPIO\_Px\_CTRL DRIVEMODE = HIGH

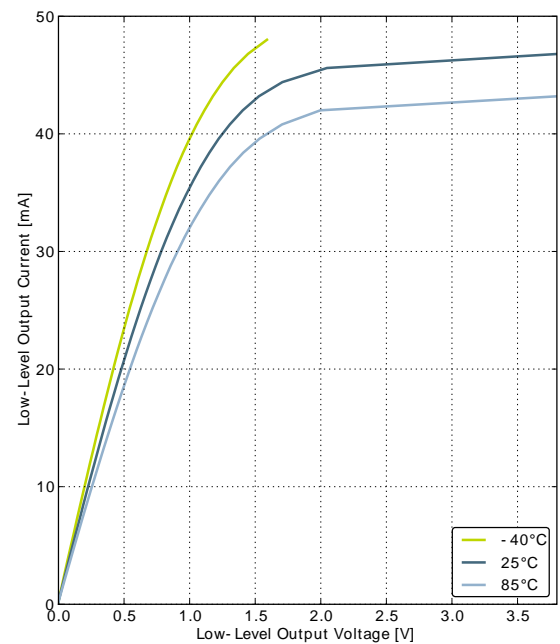
Figure 3.18. Typical Low-Level Output Current, 3.8V Supply Voltage



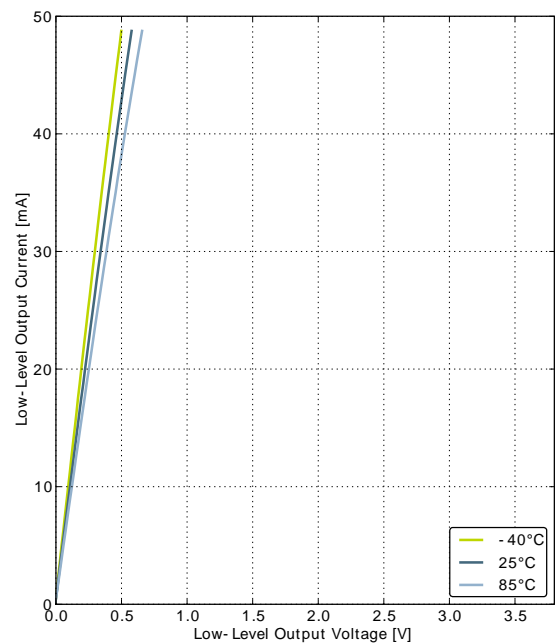
GPIO\_Px\_CTRL DRIVEMODE = LOWEST



GPIO\_Px\_CTRL DRIVEMODE = LOW

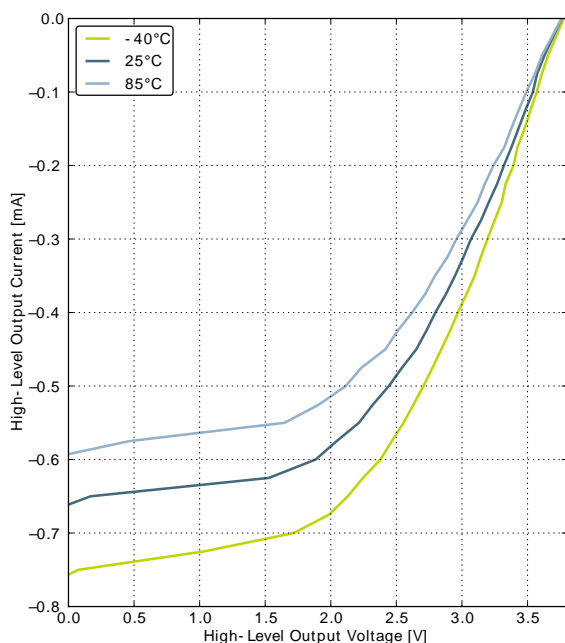


GPIO\_Px\_CTRL DRIVEMODE = STANDARD

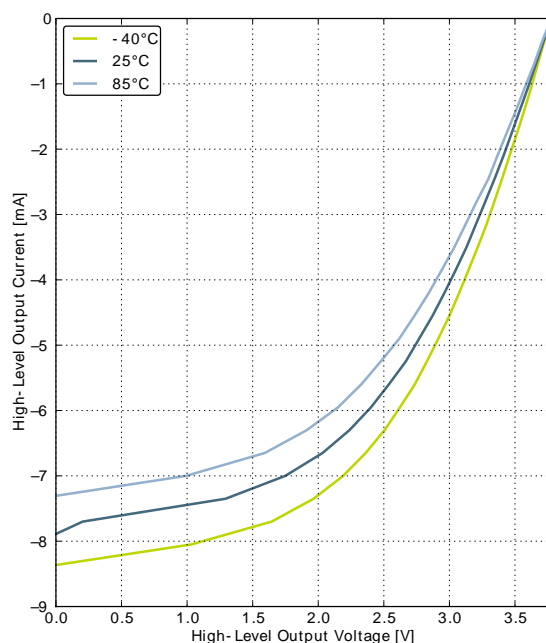


GPIO\_Px\_CTRL DRIVEMODE = HIGH

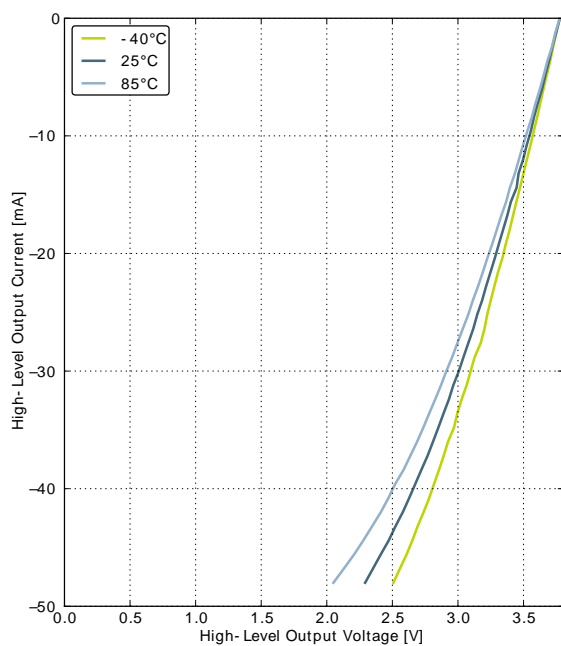
**Figure 3.19. Typical High-Level Output Current, 3.8V Supply Voltage**



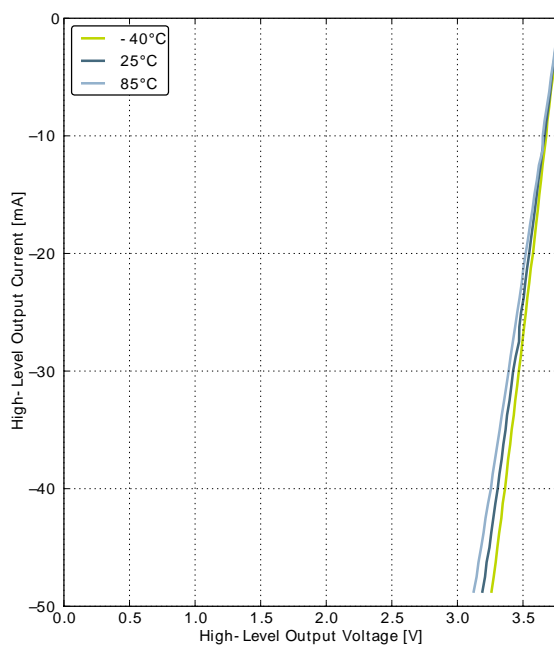
GPIO\_Px\_CTRL DRIVEMODE = LOWEST



GPIO\_Px\_CTRL DRIVEMODE = LOW



GPIO\_Px\_CTRL DRIVEMODE = STANDARD



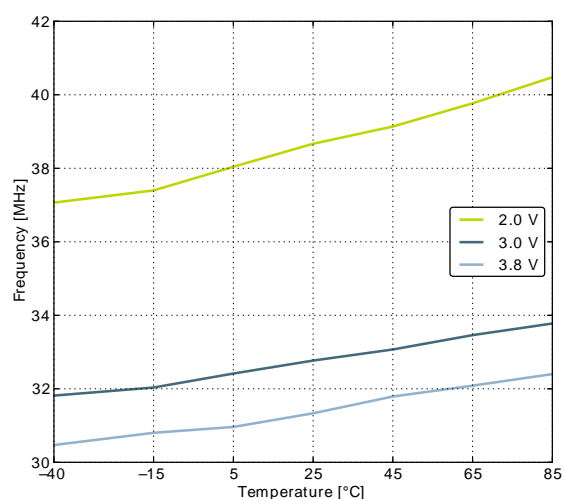
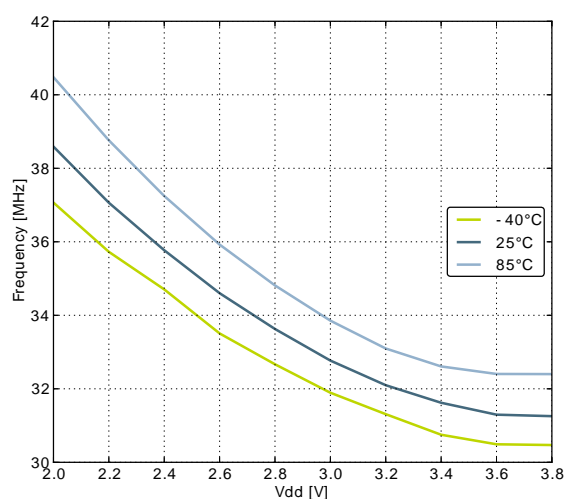
GPIO\_Px\_CTRL DRIVEMODE = HIGH

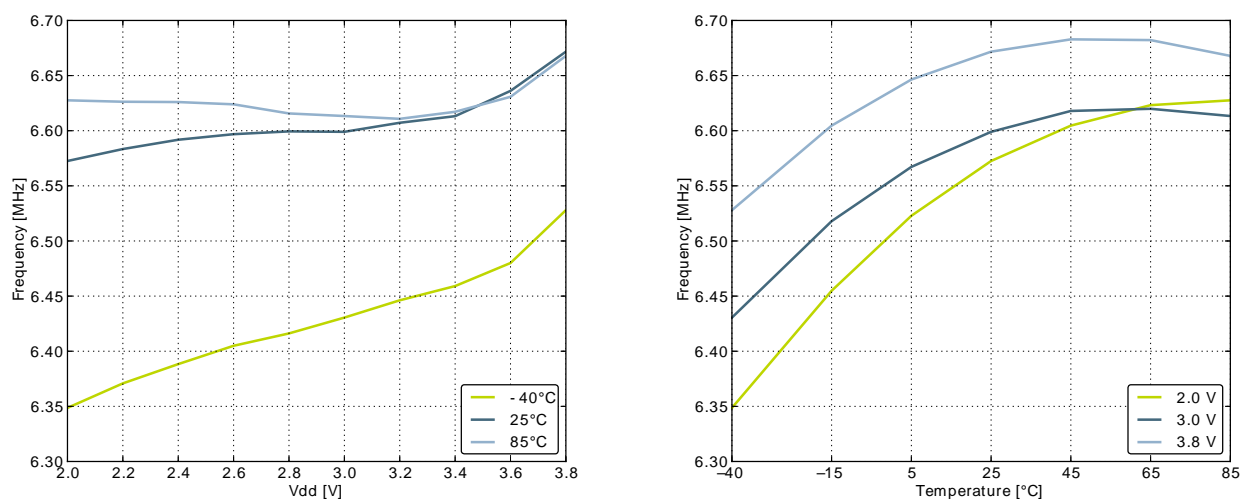
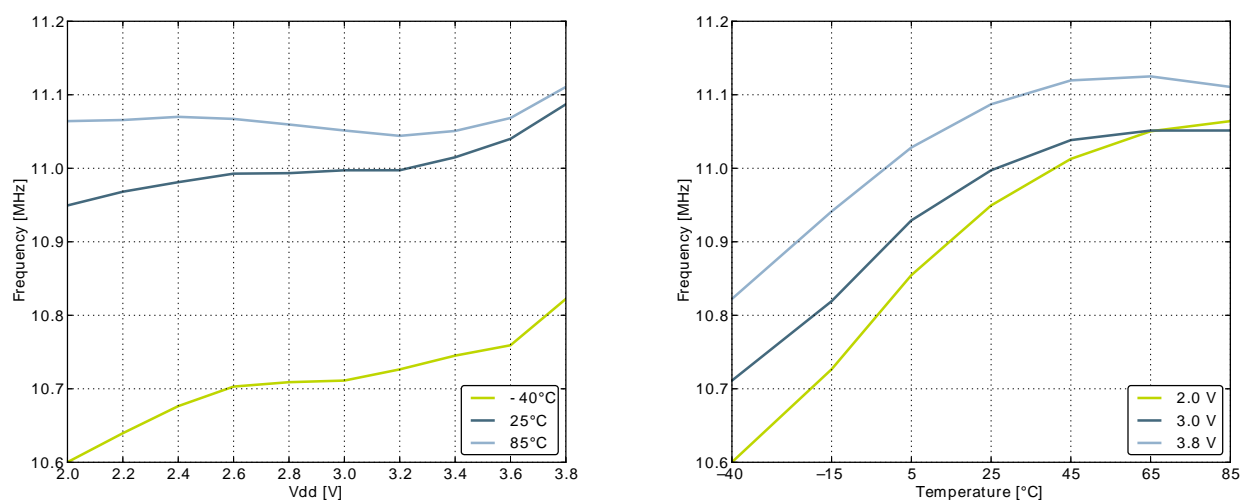
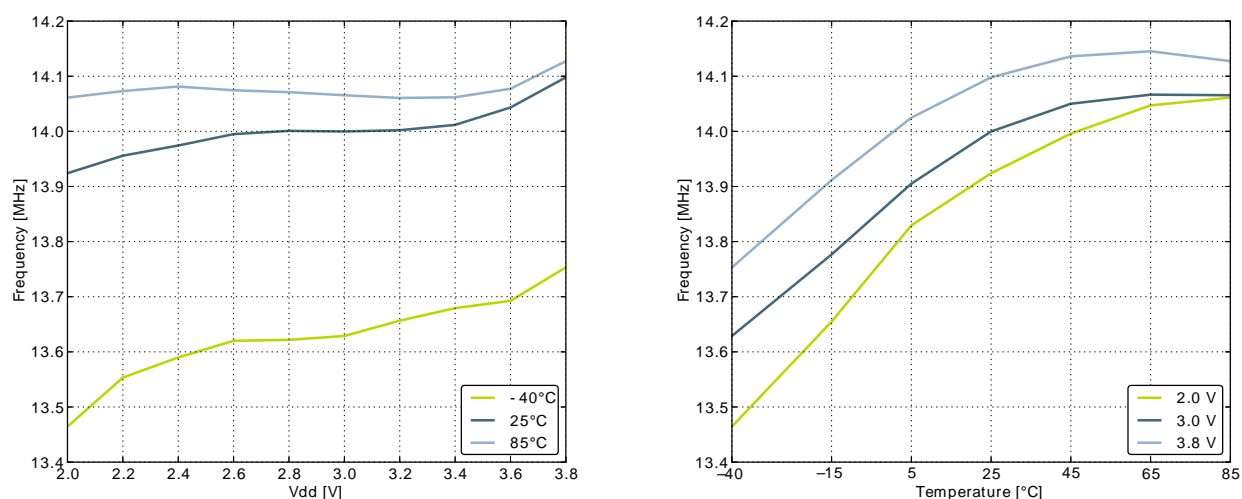
### 3.9.3 LFRCO

**Table 3.10. LFRCO**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
$f_{\text{LFRCO}}$	Oscillation frequency, $V_{\text{DD}} = 3.0 \text{ V}$ , $T_{\text{AMB}} = 25^\circ\text{C}$		31.29	32.768	34.28	kHz
$t_{\text{LFRCO}}$	Startup time not including software calibration			150		$\mu\text{s}$
$I_{\text{LFRCO}}$	Current consumption			190		nA
TUNESTEP <sub>LFRCO</sub>	Frequency step for LSB change in TUNING value			1.5		%

**Figure 3.20. Calibrated LFRCO Frequency vs Temperature and Supply Voltage**



**Figure 3.22. Calibrated HFRCO 7 MHz Band Frequency vs Supply Voltage and Temperature****Figure 3.23. Calibrated HFRCO 11 MHz Band Frequency vs Supply Voltage and Temperature****Figure 3.24. Calibrated HFRCO 14 MHz Band Frequency vs Supply Voltage and Temperature**

## 3.10 Analog Comparator (ACMP)

**Table 3.14. ACMP**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
$V_{ACMPIN}$	Input voltage range		0		$V_{DD}$	V
$V_{ACMPCM}$	ACMP Common Mode voltage range		0		$V_{DD}$	V
$I_{ACMP}$	Active current	BIASPROG=0b0000, FULL-BIAS=0 and HALFBIAS=1 in ACMPn_CTRL register		0.1	0.4	$\mu A$
		BIASPROG=0b1111, FULL-BIAS=0 and HALFBIAS=0 in ACMPn_CTRL register		2.87	15	$\mu A$
		BIASPROG=0b1111, FULL-BIAS=1 and HALFBIAS=0 in ACMPn_CTRL register		195	520	$\mu A$
$I_{ACMPREF}$	Current consumption of internal voltage reference	Internal voltage reference off. Using external voltage reference		0		$\mu A$
		Internal voltage reference		5		$\mu A$
$V_{ACMPOFFSET}$	Offset voltage	BIASPROG= 0b1010, FULL-BIAS=0 and HALFBIAS=0 in ACMPn_CTRL register	-12	0	12	mV
$V_{ACMPHYST}$	ACMP hysteresis	Programmable		17		mV
$R_{CSRES}$	Capacitive Sense Internal Resistance	CSRESSEL=0b00 in ACMPn_INPUTSEL		39		kOhm
		CSRESSEL=0b01 in ACMPn_INPUTSEL		71		kOhm
		CSRESSEL=0b10 in ACMPn_INPUTSEL		104		kOhm
		CSRESSEL=0b11 in ACMPn_INPUTSEL		136		kOhm
$t_{ACMPSTART}$	Startup time				10	$\mu s$

The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference as given in Equation 3.1 (p. 32) .  $I_{ACMPREF}$  is zero if an external voltage reference is used.

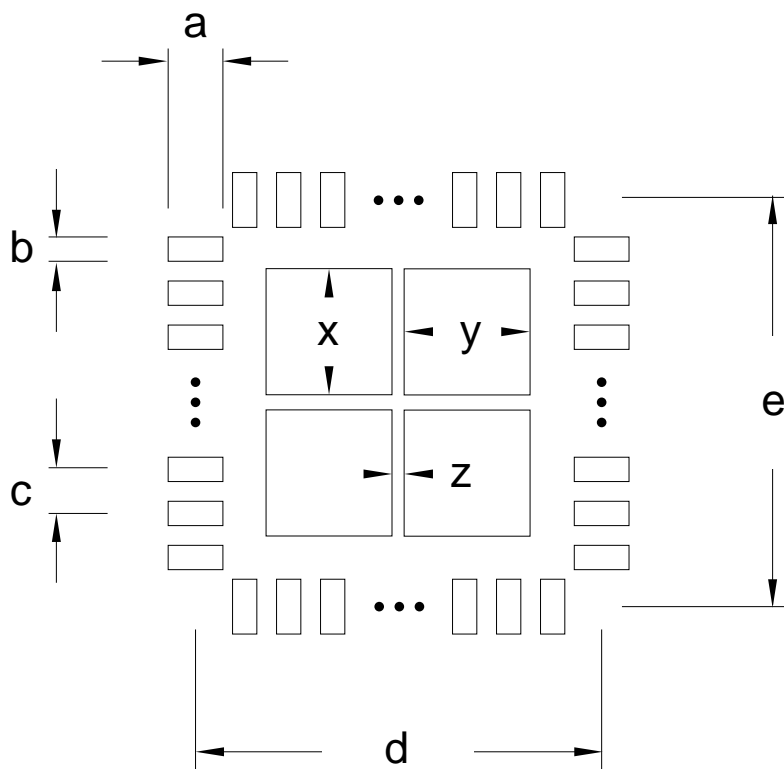
### Total ACMP Active Current

$$I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF} \quad (3.1)$$



**Table 4.2. Alternate functionality overview**

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_O	PE13		PD6					Analog comparator ACMP0, digital output.
BOOT_RX	PF1							Bootloader RX.
BOOT_TX	PF0							Bootloader TX.
CMU_CLK0			PD7					Clock Management Unit, clock output number 0.
CMU_CLK1			PE12					Clock Management Unit, clock output number 1.
DBG_SWCLK	PF0							Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1							Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFX TAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFX TAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL		PD7			PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6			PC0	PF0	PE12	I2C0 Serial Data input / output.
LEU0_RX		PB14		PF1	PA0			LEUART0 Receive input.
LEU0_TX		PB13		PF0	PF2			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN			PC0	PD6				Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1	PD7				Pulse Counter PCNT0 input number 1.
PRS_CH0	PA0		PC14					Peripheral Reflex System PRS, channel 0.
PRS_CH1			PC15					Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0							Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1							Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0			PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1					PC0	PF1		Timer 0 Capture Compare input / output channel 1.
TIM0_CC2					PC1	PF2		Timer 0 Capture Compare input / output channel 2.
TIM1_CC0				PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14			PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11				Timer 1 Capture Compare input / output channel 2.
US1_CLK	PB7		PF0	PC15				USART1 clock input / output.
US1_CS	PB8		PF1	PC14				USART1 chip select input / output.
US1_RX	PC1		PD6	PD6				USART1 Asynchronous Receive.

**Figure 5.3. QFN24 PCB Stencil Design****Table 5.3. QFN24 PCB Stencil Design Dimensions (Dimensions in mm)**

Symbol	Dim. (mm)	Symbol	Dim. (mm)
a	0.60	e	5.00
b	0.25	x	1.00
c	0.65	y	1.00
d	5.00	z	0.50

1. The drawings are not to scale.
2. All dimensions are in millimeters.
3. All drawings are subject to change without notice.
4. The PCB Land Pattern drawing is in compliance with IPC-7351B.
5. Stencil thickness 0.125 mm.
6. For detailed pin-positioning, see Figure 4.2 (p. 40) .

## 5.2 Soldering Information

The latest IPC/JEDEC J-STD-020 recommendations for Pb-Free reflow soldering should be followed.

The packages have a Moisture Sensitivity Level rating of 3, please see the latest IPC/JEDEC J-STD-033 standard for MSL description and level 3 bake conditions. Place as many and as small as possible vias underneath each of the solder patches under the ground pad.

## A Disclaimer and Trademarks

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## List of Tables

1.1. Ordering Information .....	2
2.1. Configuration Summary .....	6
3.1. Absolute Maximum Ratings .....	8
3.2. General Operating Conditions .....	8
3.3. Current Consumption .....	9
3.4. Energy Modes Transitions .....	17
3.5. Power Management .....	18
3.6. Flash .....	18
3.7. GPIO .....	18
3.8. LFXO .....	27
3.9. HFXO .....	27
3.10. LFRCO .....	28
3.11. HFRCO .....	29
3.12. AUXHFRCO .....	31
3.13. ULFRCO .....	31
3.14. ACMP .....	32
3.15. VCMP .....	34
3.16. I2C Standard-mode (Sm) .....	34
3.17. I2C Fast-mode (Fm) .....	35
3.18. I2C Fast-mode Plus (Fm+) .....	35
3.19. Digital Peripherals .....	35
4.1. Device Pinout .....	37
4.2. Alternate functionality overview .....	39
4.3. GPIO Pinout .....	40
4.4. QFN24 (Dimensions in mm) .....	41
5.1. QFN24 PCB Land Pattern Dimensions (Dimensions in mm) .....	42
5.2. QFN24 PCB Solder Mask Dimensions (Dimensions in mm) .....	43
5.3. QFN24 PCB Stencil Design Dimensions (Dimensions in mm) .....	44